# Force mos Matsuki Electric



Super high density cell design for extremely low RDS(ON)

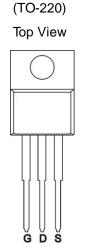
Exceptional on-resistance and maximum DC current

# N-Channel 150-V (D-S) MOSFET

### **GENERAL DESCRIPTION**

The ME100N15T-G is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching, and low in-line power loss are needed in a very small outline surface mount package.

### PIN CONFIGURATION



Ordering Information: ME100N15T-G (Green product-Halogen free)

# Absolute Maximum Ratings (Tc=25°C Unless Otherwise Noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		Vdss	Vdss 150	
Gate-Source Voltage		Vgss	±20	V
Continuous Drain Current*	<b>Tc=25</b> ℃	1-	72.3	
	Tc=70°C	lD	57.8	- A
Single pulse Avalanche Energy L=0.5mH	<b>Tc=25</b> ℃	las	50	А
Single pulse Avalanche Energy L=0.5mH	<b>Tc=25</b> ℃	Eas	625	mJ
Pulsed Drain Current <sup>a</sup>		ldм	Ідм 289	
	Tc=25℃	<b>_</b>	113.6	
Power Dissipation	Tc <b>=70</b> ℃	PD -	72.7	- W
Operating Junction and Storage Temperature Range		TJ, Tstg	-55 to 175	°C
Thermal Resistance-Junction to Case**		Rejc	1.1	°C/W

\* Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 120A.

\*\* The device mounted on 1in<sup>2</sup> FR4 board with 2 oz copper.

Jul, 2016-Ver1.3

# G ⊶

FEATURES

capability

**APPLICATIONS** 

DC/DC Converter

LCD Display inverter

Load Switch

0

• RDS(ON)  $\leq$  13.6m $\Omega$ @VGS=10V

Power Management in Note book

D

N-Channel MOSFET

Matsuki Electric



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## Electrical Characteristics (Tc = 25°C Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Тур	Max	Unit
STATIC						
BVDSS	Drain-Source Breakdown Voltage	Vgs=0V, Id=250 μ A	150			V
VGS(th)	Gate Threshold Voltage	Vbs=Vgs, Ib=250 μ A	2.0		4.0	V
lgss	Gate-Body Leakage	VDS=0V, VGS=±20V			±100	nA
IDSS	Zero Gate Voltage Drain Current	VDS=150V, VGS=0V			1	μA
RDS(ON)	Drain-Source On-Resistance*	Vgs=10V, Id=62A		11.3	13.6	$\mathbf{m}\Omega$
Vsd	Diode Forward Voltage *	Is=62A, Vgs=0V			1.3	V
gfs	Forward Transconductance	Vds=20V, Id=36A		22		S
DYNAMIC		·				
Qg	Total Gate Charge	VDS=75V, VGS=10V, ID=62A		333		nC
Qg	Total Gate Charge			91.6		
Qgs	Gate-Source Charge	VDS=75V, VGS=4.5V, ID=62A		115		
Qgd	Gate-Drain Charge			75.2		
Rg	Gate-Resistance	VDS=0V, VGS=0V, f=1MHz		3.3		Ω
Ciss	Input Capacitance			20776		pF
Coss	Output Capacitance	VDS=30V, VGS=0V, f=1MHz		597		
Crss	Reverse Transfer Capacitance			523		
td(on)	Turn-On Delay Time			68.4		- ns
tr	Turn-On Rise Time	VDS=75V, RL=1.2Ω		54.7		
<b>t</b> d(off)	Turn-Off Delay Time			300		
tr	Turn-Off Fall Time			57.6		

Notes: a, pulse test: pulse width  $\leq$  300us, duty cycle  $\leq$  2%, Guaranteed by design, not subject to production testing.

b. Matsuki / Force mos reserves the right to improve product design, functions and reliability without notice.

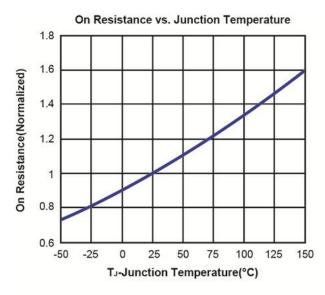


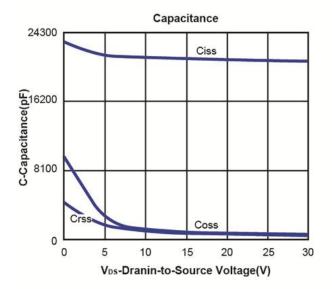


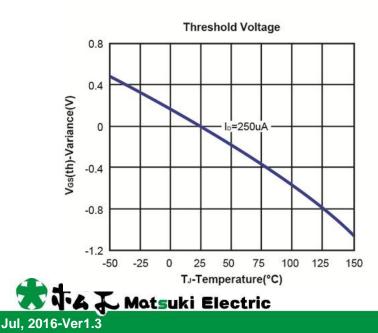


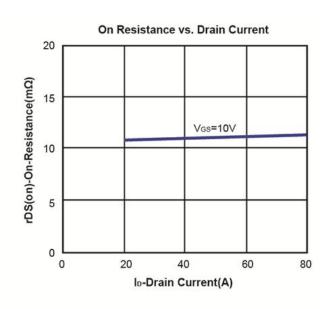
# N-Channel 150-V (D-S) MOSFET

# Typical Characteristics (TJ =25℃ Noted)

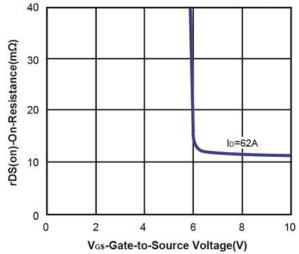




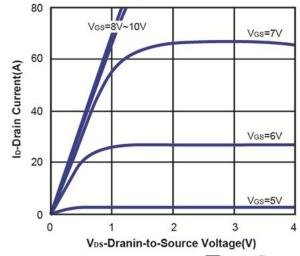




On Resistance vs. Gate-to-Source Voltage

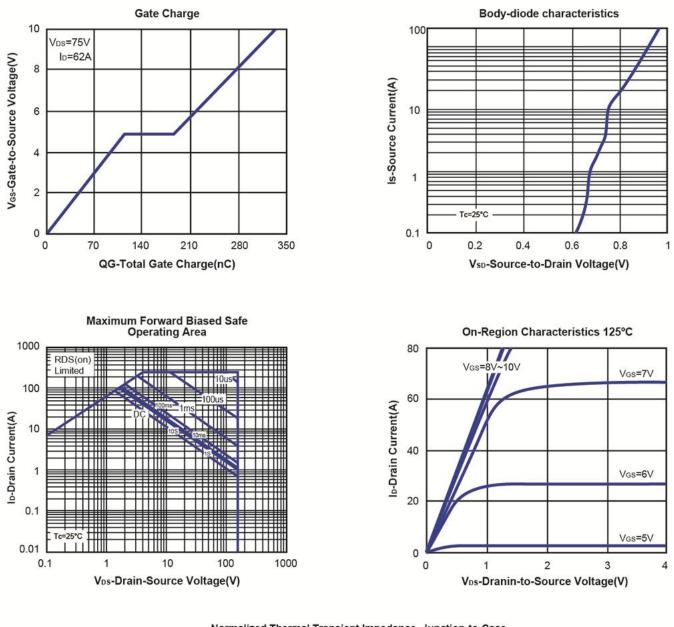




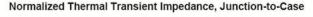


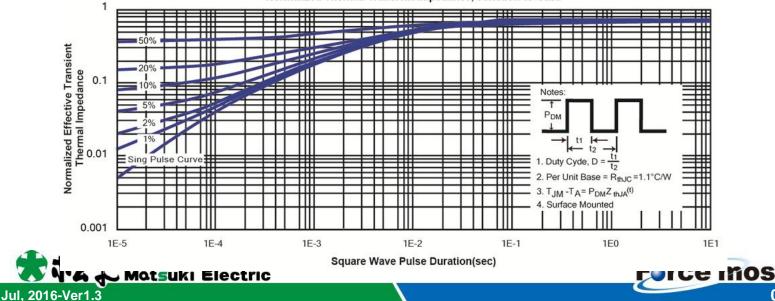


N-Channel 150-V (D-S) MOSFET



# Typical Characteristics (TJ =25℃ Noted)





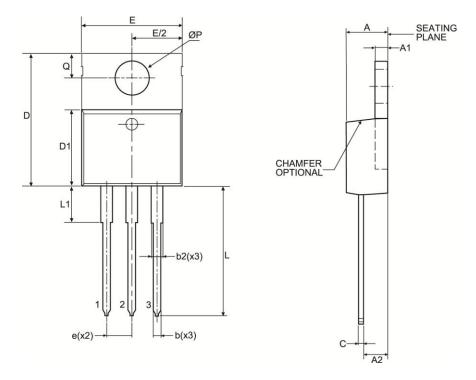






N-Channel 150-V (D-S) MOSFET





C	MILLIMETERS (mm)			
Symbol	MIN	MAX		
А	3.50	4.90		
A1	1.00	1.40		
A2	2.00	3.00		
b	0.70	1.40		
С	0.35	0.65		
D	14.00	16.50		
D1	8.30	9.50		
E	9.60	10.70		
e	2.54 BSC			
L	12.50	15.00		
ØP	3.60 TYP			
Q	2.50	3.10		
b2	1.10	1.80		
L1	2.40	3.20		



